Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	3 X 3 X 0.75
Lead Count	16
Terminal Finish	NiPdAu
MS Number	MS012105

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	9.98E-03	86.91	869100	49.16	491616
Thermosets	Epoxy & Phenol Resin	Proprietary	1.47E-03	12.78	127800	7.23	72292
Other inorganic materials	Carbon black	1333-86-4	3.56E-05	0.31	3100	0.18	1754
Subtotal			1.15E-02	100.00	1000000	56.57	565661

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	7.79 E-03	96.20	962000	38.38	383756
Copper & its alloys	Nickel	7440-02-0	2.43 E-04	3.00	30000	1.20	11967
Copper & its alloys	Silicon	7440-21-3	5.26 E-05	0.65	6500	0.26	2593
Copper & its alloys	Magnesium	7439-95-4	1.21 E-05	0.15	1500	0.06	598
Subtotal			8.10 E-03	100.00	1000000	39.89	398915

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	1.95 E-04	97.3	972697	0.96	9623
Precious metals	Palladium	7440-05-3	4.54 E-06	2.3	22621	0.02	224
Precious metals	Gold	7440-57-5	9.40 E-07	0.5	4683	0.00	46
Subtotal			2.01 E-04	100.00	1000000	0.99	9893

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	4.28 E-05	99.0	990000	0.211	2106
Precious Metals	Palladium	7440-05-3	4.32 E-07	1.0	10000	0.002	21
Subtotal			4.32 E-05	100.0	1000000	0.21	2128

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.56 E-04	100.0	1000000	1.76	17552

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	8.31 E-05	70.00	700000	0.41	4096
Other organic materials	Resin	Proprietary	1.78 E-05	15.00	150000	0.09	878
Others	Additive	Proprietary	1.19 E-05	10.00	100000	0.06	585
Other organic materials	Bisphenol A Glycidylether	25068-38-6	5.94 E-06	5.00	50000	0.03	293
Subtotal			1.19 E-04	100.0	1000000	0.59	5851

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.03 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES